



Material Content Data Sheet



Sales Product Name		TLE7274-2D		Issued		25. September 2017			
MA#		MA000509870							
Package		PG-TO252-3-11		Weight*		371.11 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.671	0.45	0.45	4504	4504	
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		580		
	inorganic material	phosphorus	7723-14-0	0.065	0.02		174		
	non noble metal	copper	7440-50-8	215.017	57.93	58.01	579396	580150	
wire	non noble metal	aluminium	7429-90-5	0.114	0.03	0.03	306	306	
encapsulation	organic material	carbon black	1333-86-4	1.914	0.52		5158		
	plastics	epoxy resin	-	21.056	5.67		56739		
	inorganic material	silicondioxide	60676-86-0	104.642	28.20	34.39	281975	343872	
leadfinish	non noble metal	tin	7440-31-5	3.787	1.02	1.02	10204	10204	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		245		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	246	
solder	noble metal	silver	7440-22-4	0.083	0.02		224		
	non noble metal	tin	7440-31-5	0.067	0.02		179		
	non noble metal	lead	7439-92-1	3.180	0.86	0.90	8570	8973	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		52		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16		
	non noble metal	copper	7440-50-8	19.177	5.17	5.18	51677	51745	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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